



Evolution of the Sequana System Architecture The Past, the Present and the Future

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Content overview

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Sequana 1: X1000 Q&A

JUWELS Cluster

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Sequana 2: XH2000

JUWELS Booster, JURECA-DC

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Sequana 3: XH3000

JUPITER

Pre Sequana Era

Bull B700 DLC Solution



- Chassis based approach
- Direct Liquid Cooling on blades and switches
- Design with 9 blades (18 nodes) per Chasssis was directly linked to 36-Port IB Switches
- Many Sequana features already present:
 - All in one approach
 - Central Power (54C DC)
 - Free Cooling & Heat reuse
- Installations in Germany
 - TU-Dresden: Taurus
 - DKRZ Hamburg: Mistral





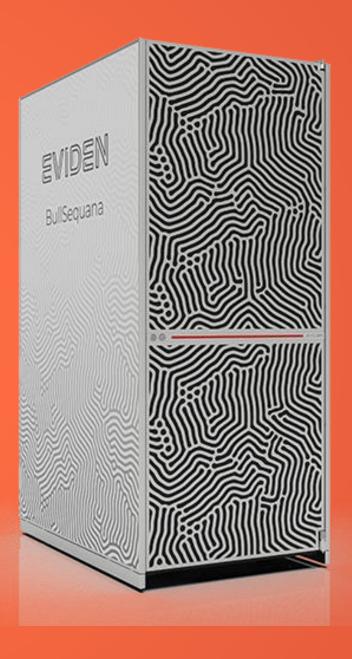






The Past:

Sequana 1 - X1000



Bull Sequana X1000

the Bull exascale generation of supercomputer

- Open and modular platform designed for the long-term
 - To preserve customer investments
 - To integrate current and future technologies
 - Multiple compute nodes: Xeon-EP, Xeon Phi, Nvidia GPUs, other architectures...
- Scales up to tens of thousands of nodes
 - Large building blocks to facilitate scaling
 - Large systems with DLC: 250-64k nodes
- Embedding the fastest interconnects
 - Multiple Interconnects: BXI, InfiniBand EDR/HDR
 - Optimized interconnect topology for large basic cell / DLC (288 nodes)
 - Fully non-blocking within Cell
- Ultra-energy efficient
 - Enhanced DLC up to 40°C for inlet water and ~100% DLC



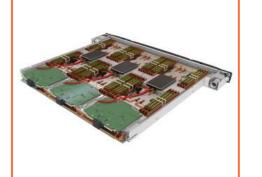




Bull Sequana X1000 cell technology

Bull Sequana X1000 cell





support several types and generations of compute nodes either with conventional processors or with accelerators

3 cabinets

- 2 compute cabinets
- 1 x L1 & L2 interconnect switches and management server cabinet

Up to 288 compute nodes (96 blades)

- Supports Intel Xeon Broadwell-EP processor
- Supports Intel XeonPhi Knights Landing (KNL) processor
- Supports Intel Xeon Skylake-EP processor
- Supports Nvidia GPU Pascal accelerator

2 interconnect technologies supported

- InfiniBand EDR
- Bull eXascale Interconnect (BXI)

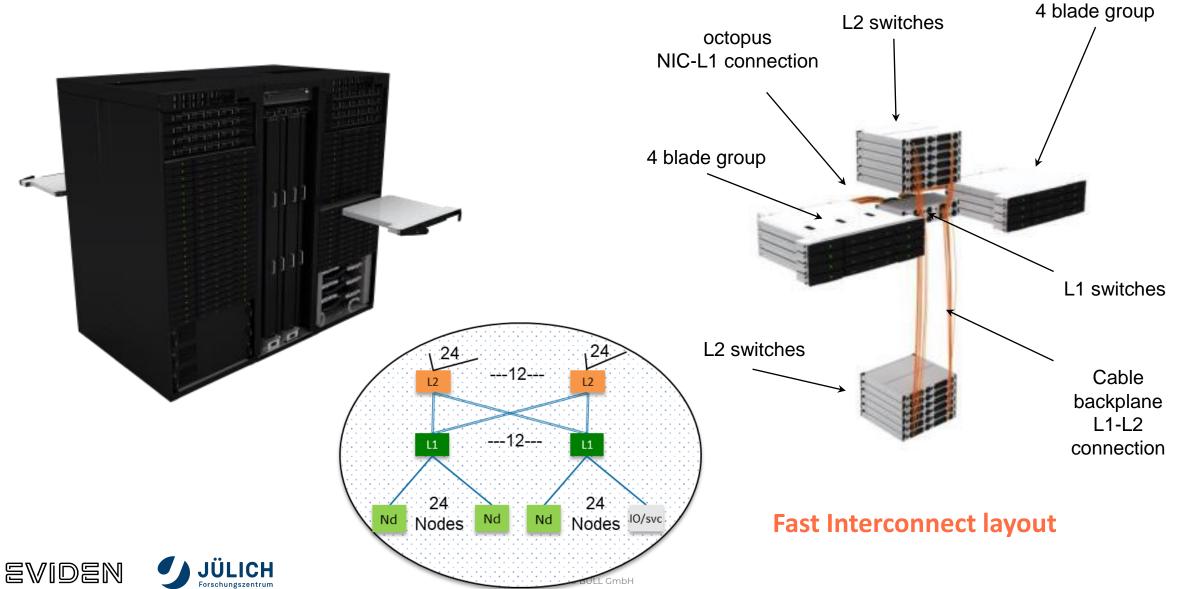
Full Direct Liquid Cooling

- compute blades
- L1 & L2 interconnect switches
- Power supplies (end 2016)

Island Management and Administration

- Redundant server with
- Shared storage

Bull Sequana X1000 – embedded interconnect



Bull Sequana X1000 (JUWELS Cluster)

Lessons Learned

PRO:

- Modular system platform
- Blade system
- Multiple blade types
- Cell Concept as building block
- Direct Liquid Cooling
- Up to 40°C warm water as inlet temperature (free cooling)
- All in one approach (Compute, interconnect, power, cooling)

CON:

- Fixed Cell Size (288 nodes) as building block
- Fixed interconnect topology (L1 and L2)
- Proprietary switch design
- Missing flexibility with EDR (only 2:1 Fat-Tree)
- Air-Cooled components (ISMAs, PSUs)



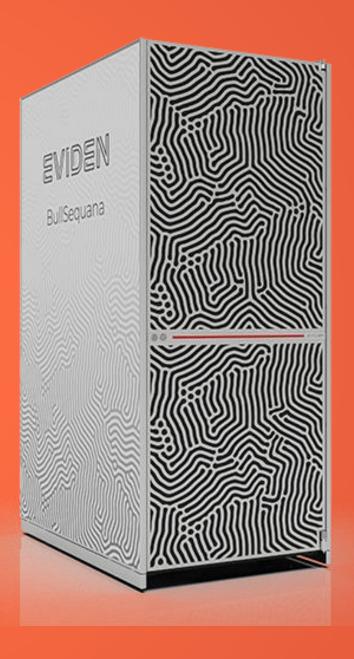






The Present:

Sequana 2 – XH 2000



What is BullSequana XH2000?

A new generation of Sequana X1000



- XH2000 is not a new machine, it is a natural evolution of X1000:
 - XH2000 is compatible with existing and future blades
 - XH2000 reuse as much as possible X1000 components in order to protect Atos investments
 - XH2000 will be able to scale to Exascale
- XH2000 leads to cost optimization
- XH2000 embeds new features:
 - XH2000 introduces support for new technologies such as Mellanox HDR, new fabric topologies, new pruning ratios, Fast Ethernet
 - XH2000 improves infrastructure costs by at least 10% compared to X1000
 - XH2000 provides access to new markets:
 - Entry level configurations
 - Configurations up to 800 nodes should be installed (SW) in less than 3 days
 - XH2000 provides optional redundancy features (compared to X1000 where they are embedded)

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BullSequana XH2000 Overview



One 42U cabinet with:

- up to 32 compute DLC blades / 96 compute nodes
 - 20 on front side, 12 on rear side
- up to 6 liquid-cooled PSU shelves (up to 30 liquid cooled PSUs)
- fanless design
- 2 HYC, optional 3rd HYC for 2+1 redundancy
- 2 Leaf Ethernet modules
- Up to 10 Interconnect DLC Switches
 - HDR100 & HDR200 in Phase 1
 - BXI and Fast Ethernet in Phase 2
- 1 Power distribution unit with 3x 63A tri-phase cables
- Power and signal connections at the top of rack

Power and cooling capacity: 15 to 90kW

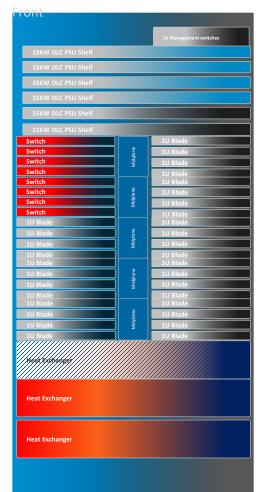




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BullSequana XH2000 Details

Side View



Front View



Rear View

PDU + Power controller up to 6 x 15KW DLC shelves (Optional redundancy) 2 x Leaf Eth switches

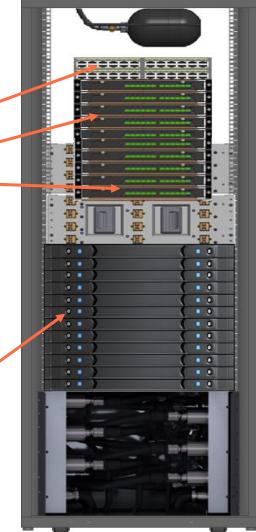
up to 10 switches

4 to 20 compute blades

up to 12 compute blades

up to 3 Hydraulic chassis (2+1 optional redundancy)









BullSequana XH2000 Networking

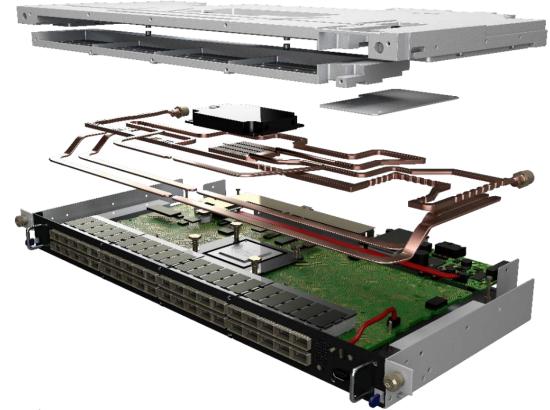
New HDR interconnect

DLC cooled Mellanox HDR switch

- 40 X HDR 200Gb/s ports in a 1U switch
- 80 X HDR100 100Gb/s ports in a 1U switch
- 16Tb/s aggregate switch throughput
- Up to 15.8 billion messages-per-second
- 90ns switch latency
- Atos Cold Plate DLC

HDR Flexible Sideplane

- 4 blades / up to 12 nodes HDR Sideplane
- QSFP connectors, HDR and HDR100 option (Y cables in SOH)
- Single connector for Sideband and management (up to 12 nodes)

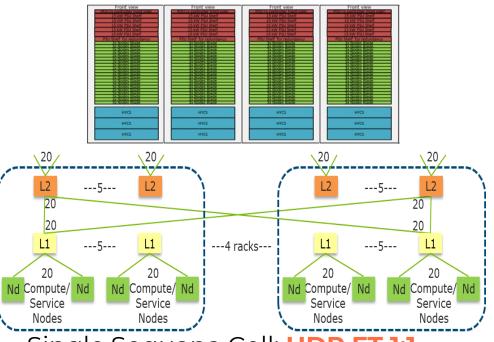






BullSequana XH2000 Topology options

Cell Design: NON BLOCKING Fat Tree (HDR & HDR100)

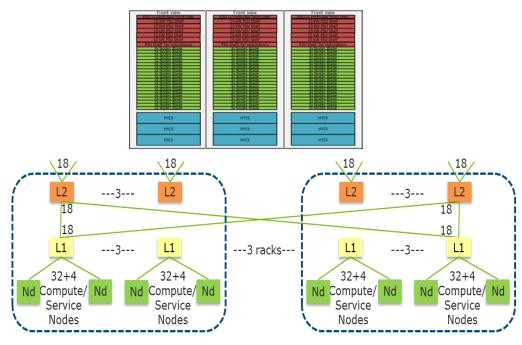


Single Sequana Cell: HDR FT 1:1

- 4 racks
- 384 Compute Nodes
- 40 HDR switches
- 9,6 CN/SW







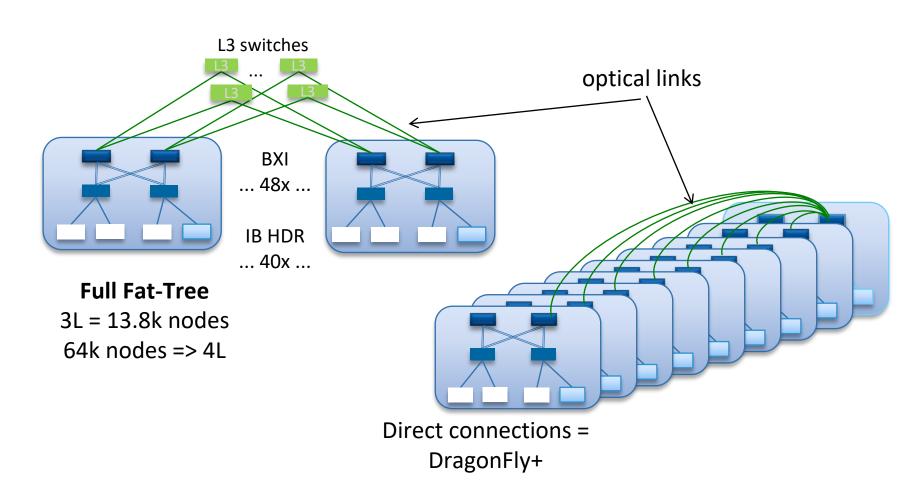
Single Sequana Cell: HDR100 FT 1:1

- 3 racks
- 288 Compute Nodes +18-36 IO
- 18 HDR switches
- 16 CN/SW

BullSequana XH2000 Networking

Best in class Interconnect flexibility







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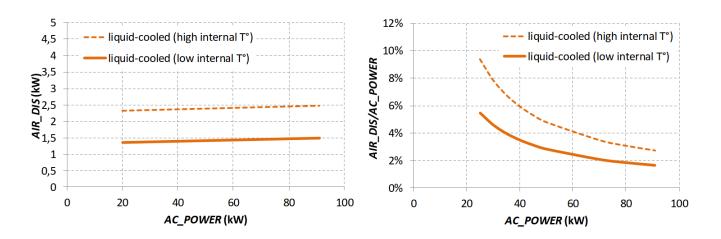
BullSequana XH2000 Cooling

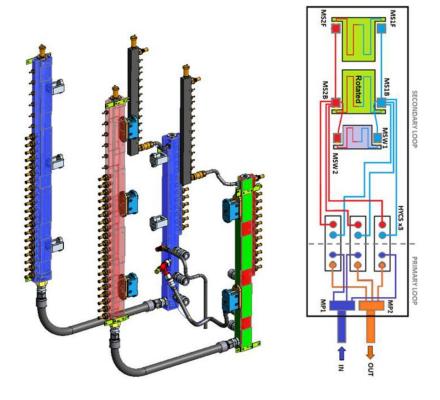
Optimized Power Usage Effectiveness

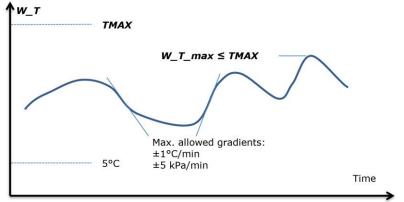
BullSequana XH2000: > 95% cooling efficiency

Fan less architecture:

- Warm water up to 40°C (104°F) inlet
- Heat rejected in air is almost constant
 - Pumps, radiation and normal convection ~1,5 kW / rack to 2,5kW / rack
 - DC power heat rejection : 0,5% of the power consumption
- 2 modes of operation: low & high internal temperature











Bull Sequana XH2000 (JUWELS Booster, JURECA-DC)

Lessons Learned

PRO:

- Modular system platform
- Blade system
- Multiple blade types
- Switch blade based on standard technology
- Rack (96 nodes) as technological building block
- Cell Concept as logical building block
- Direct Liquid Cooling (fanless rack)
- Up to 40°C warm water as inlet temperature (free cooling)
- All in one approach (Compute, interconnect, power, cooling)

CON:

- 90kW power not sufficient for future technology
- Using Midplane for the high speed interconnect can be a limitation
- Different form factor for compute and switch blades can be a limitation – or leads to ineffective use of rack space



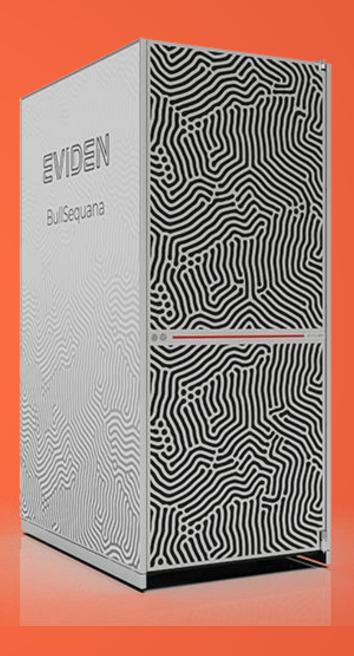






The Future (Now):

Sequana 3 – XH 3000



BullSequana X high-end platform evolution

Relentless pursuit to bring more performance and flexibility to our customers



BullSequana X1000

- 2nd generation DLC
- 40°C inlet water temperature support
- Increased density
- Designed to better scale to large Petascale systems
- Support of InfiniBand HDR high-speed interconnect technology

BullSequana XH2000

- 3rd generation DLC with introduction of DLC PSUs
- "All-In-One" Rack form factor to support smaller systems all the way up to Exascale systems
- Increased flexibility of compute and interconnect technologies supported
- Support of InfiniBand HDR highspeed interconnect technology

BullSequana XH3000

- 4th generation DLC
- Substantial increase of power and cooling envelope
- Increased flexibility of compute and interconnect technologies supported
- Support of InfiniBand NDR high-speed interconnect technology
- Standardized design to support OpenSequana program





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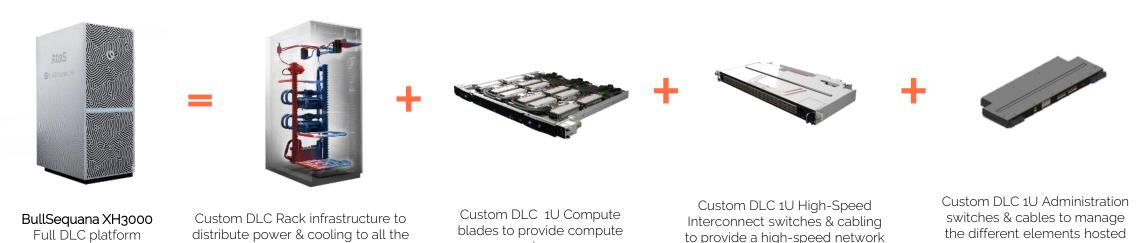
BullSequana XH3000

A fully integrated Direct Liquid Cooled (DLC) custom platform

BullSequana XH3000 is an Atos custom designed platform that integrates:

elements hosted within the rack

- DLC ready infrastructure with power and cooling distribution,
- DLC compute nodes (or servers),
- · DLC high-speed interconnect switches with high-speed cabling, and
- DLC administration switches



• All components within the rack are DLC with warm water up to 40°C to provide maximum performance, density and the lowest Total Cost of Ownership possible

processing power.





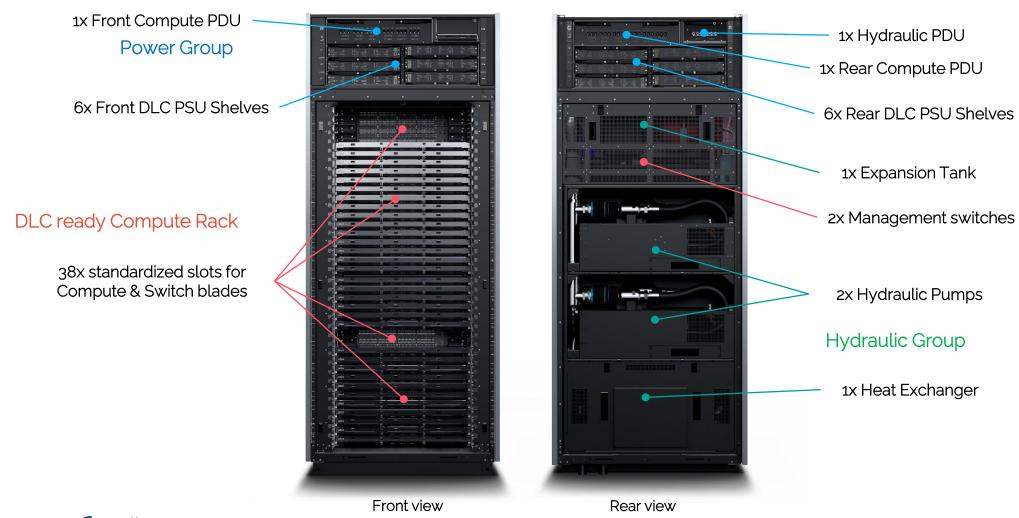
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to exchange data between compute blades

within the rack

BullSequana XH3000 Infrastructure overview

Architecture Overview



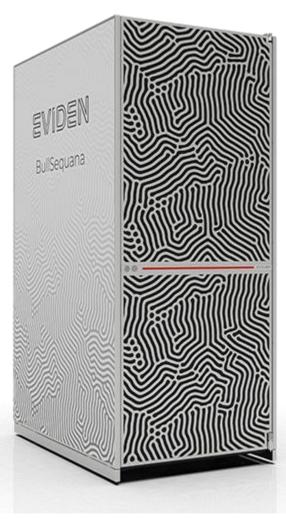




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BullSequana XH3000 Cooling

Optimized Power Usage Effectiveness



BullSequana XH3000: a fanless innovative cooling solution

Direct Liquid Cooling:

- Compute nodes (CPU, Memory, Drives, GPU)
- High Speed Interconnect: HDR, BXI & High-Speed Ethernet switches
- Management network: Intra Rack management switches
- Power Supply Unit: DLC PSU shelves
- No need for external CDU, they are integrated and redundant

XH3000 HYCS's pumps are not liquid cooled but are still fanless

Two Internal Regulation Temperature modes:

Low Internal temperature

- High flow rate
- Outlet temp depend on Inlet
- Lower Air dissipation

High Internal temperature

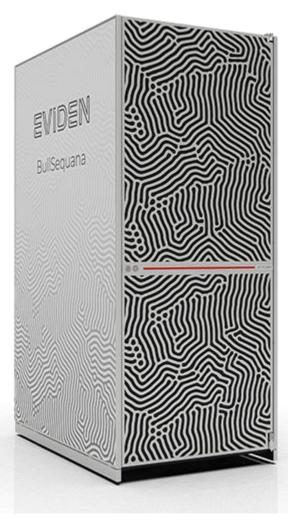
- Low flow rate
- Outlet temp always at max.
- Heat reuse





BullSequana XH3000 Cooling

Optimized Power Usage Effectiveness



BullSequana XH3000: >97% Warm Water Cooled

Fan less architecture:

- Warm water up to 40°C inlet
- · Heat rejected in air is almost constant
 - Pumps, radiation and normal convection ~1,5 kW / rack to 2,5kW / rack
 - DC power heat rejection : 0,3%-0,5% of the power consumption

Full rack running linpack: 120 kW

- 97% efficiency at Low Internal temperature: 3,6 kW Air dissipation
- 95% efficiency at High Internal temperature: 6 kW Air dissipation

Full rack 1/3 of load: 40 kW

- 92% efficiency at Low Internal temperature: 3,2 kW Air dissipation
- 87% efficiency at High Internal temperature: 5,2 kW Air dissipation



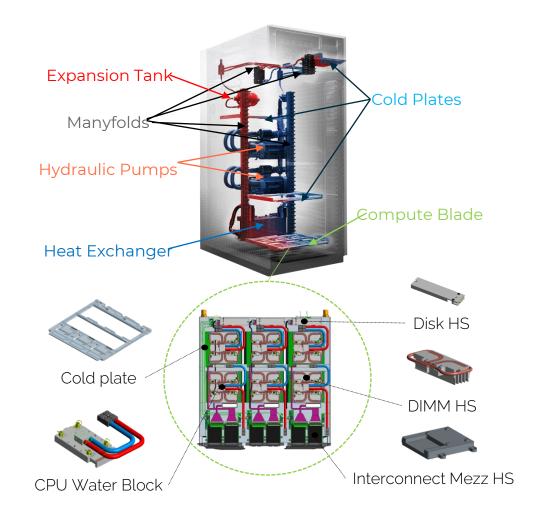


BullSequana XH3000 Infrastructure

Hydraulic architecture overview

Hydraulic architecture is composed of several elements:

- That are part of the rack:
 - 2 hydraulic pump modules managed by 2 HMCs
 - 1 common heat exchanger with 2 primary valves
 - 2 sets of manifolds:
 - One for compute, switch and administration blades
 - One for power shelves
 - 1 expansion tank
- That are part of the blades:
 - Water blocks for CPU/GPU cooling in compute blades
 - Heat spreaders for DIMM, Interconnect mezzanine and disk in compute blades
 - Cold plates for other motherboard components in compute, switch and administration blades







BullSequana XH3000 Power group

Power architecture overview

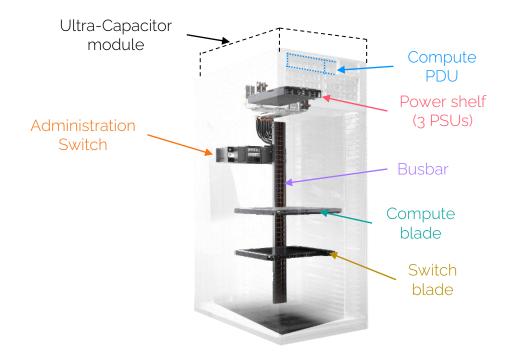
Power architecture is composed of several elements:

- Power Group P3G mounted on top of the rack:
 - Power Distribution Units (PDU): 2 compute PDUs (one at the front, one at the rear of the rack), 1 hydraulic PDU (at the front of the rack)
 - Power Shelves. One shelf contains 3 Titanium Power Supply Units of 4,2kW each. Max of 12 Power Shelves per rack (147kW + 4,2kW redundancy)
- Power distribution busbar inside the rack
- Power distribution board inside each blade
- Ultra-capacitor module mounted on top of P3G

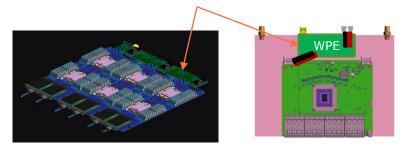
Power shelves and blades are Direct Liquid Cooled and "hot-plug"

Possibility to assemble Power group at customer site

- Standard is assembled at factory
- When height constraint in data center below 2,25m







Compute blade boards

Switch blade board







JUPITER (ExaScale)

System Architecture



System Solution





First to the future

> 6000 Compute Nodes

- > 5.000 GPU nodes
- > 20.000 Nvidia Grace/Hopper
- > 1.000 CPU Nodes
- > 2.000 Sipearl Rheal CPUs (EPI)
- > 14 PB main memory

Flash Storage

- > 20 PB
- > 2 TB/s Bandwidth

Service Nodes

- Login Nodes
- Admin & Service Nodes

High Speed Interconnect

NDR Infiniband – Fully non blocking

Footprint

- 25 Sequana Cells (5x XH3000 cabinet)
- 5 Standard Racks (Service & Flash Storage)

Energy Efficiency

- PUE factor of 1,03
- Enhanced DLC up to 40°C for inlet water and 97% DLC efficiency

Performance: 1 EFlop/s HPL

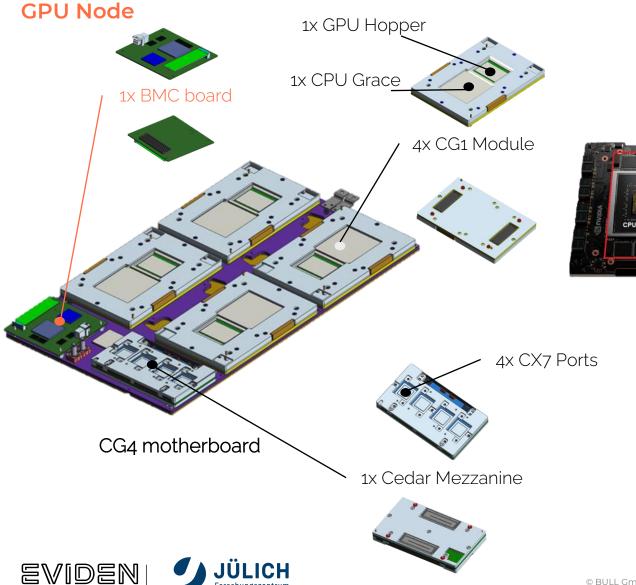


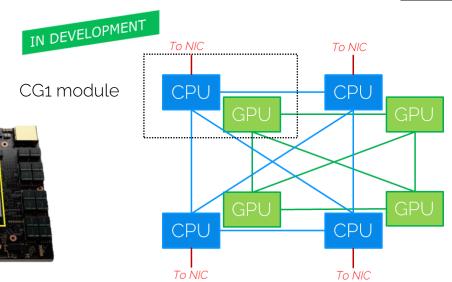


BullSequana X3515-HMQ Grace-Hopper Blade







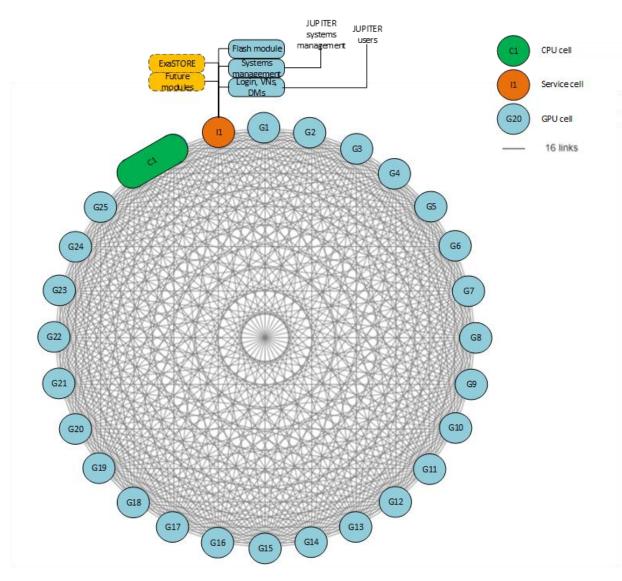


- All-to-all NVLink between CPU (C-link)
- All-to-all NVLink between GPU (G-link)
- Coherent memory space
- GPU direct access to NIC



DragonFly+ with Cluster-Cell and I/O-Cell

First to the future



IO Cell contains:

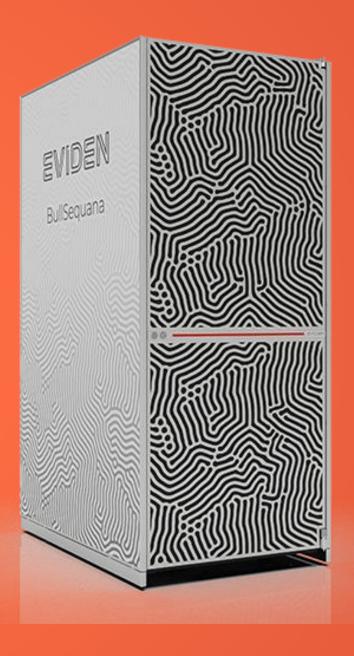
- Flash storage
- Management nodes
- Login nodes
- Any other peripheral nodes which may be needed such as pre- post- processing or visualization
- (ExaStore Storage)
- (Future Modules)







Questions?



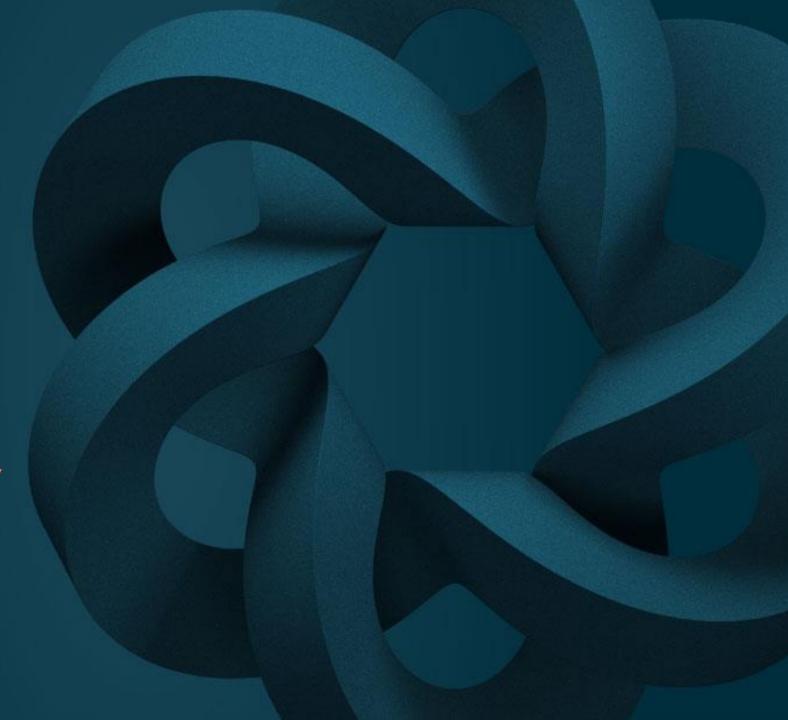
Thank you!

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